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Part Number:

0739446016

Status:

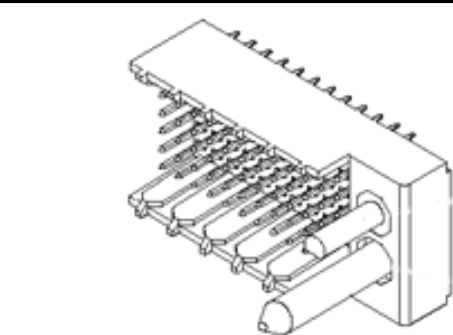
Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits



Series image - Reference only

Documents:

3D Model

Drawing (PDF)

Product Specification PS-73670-9999 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73944
Application	Backplane
Component Type	PCB Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800753005594
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	5.394/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	Yes
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

EU ELV
Not Relevant

EU RoHS
Compliant

China RoHS

REACH SVHC
Contains SVHC(2014
December 17): No

Halogen-Free
Status
Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS
ELV

Green Image
Not Relevant

Search Parts in this Series
73944 Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001
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